SCLS495-JUNE 2003

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication
- **Extended Temperature Performance of** -55°C to 125°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree[†]
- Inputs Are TTL-Voltage Compatible
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Process**
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

D OR PW PACKAGE (TOP VIEW) 14 🛮 V_{CC} 1CLR 1D [13 2CLR 1CLK [] 3 12**∏** 2D 1PRE ∏ 4 11 2CLK 1Q [10 2PRE 1Q 6 9 🛮 2Q GND [8∏2Q

description/ordering information

The SN74AHCT74 is a dual positive-edge-triggered D-type flip-flop.

A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

ORDERING INFORMATION

T _A PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–55°C to 125°C	SOIC – D	Tape and reel	SN74AHCT74MDREP	AHCT74MEP
-55 C to 125 C	TSSOP – PW	Tape and reel	SN74AHCT74MPWREP	AHT74EP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC is a trademark of Texas Instruments



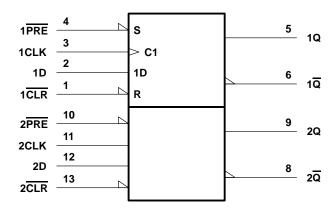
SCLS495- JUNE 2003

FUNCTION TABLE

	INP	OUTI	PUTS		
PRE	CLR	CLK	D	Q	ω
L	Н	Х	Х	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	н†	H [†]
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Х	Q ₀	\overline{Q}_0

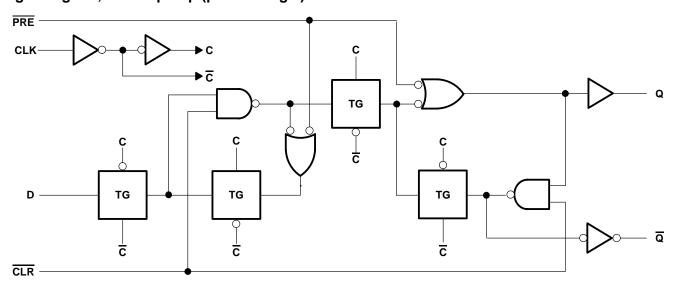
[†] This configuration is unstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

logic symbol‡



[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each flip-flop (positive logic)





SN74AHCT74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

SCLS495-JUNE 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Note 1)	
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
VI	Input voltage	0	5.5	V
Vo	Output voltage	0	VCC	V
ЮН	High-level output current		-8	mA
loL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-55	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	T,	_Δ = 25°C	;	MIN	MAV	UNIT
PARAWIETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	IVIIIN	0.1 0.44 ±1 20	UNIT
Voн	$I_{OH} = -50 \mu A$	4.5 V	4.4	4.5		4.4		V
VOH	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		V
\/o!	I _{OL} = 50 μA	4.5 V			0.1		0.1	V
VOL	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.1 0.44 ±1 20	V
lį	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
Δl _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		2	10			pF

[‡]This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN74AHCT74-EP **DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH CLEAR AND PRESET

SCLS495- JUNE 2003

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

	PARAMETER		T _A = 25°C		MIN	MAX	UNIT		
	PARAMETER	MIN	MAX	IVIIN	WAX	UNII			
t	Pulse duration	PRE or CLR low	5		5		nc		
t _W	ruise duration	CLK	5		5		ns		
	Oaton the hoters OLKA	Data	5		5				
t _{SU} Setup time before CLK↑	3.5		3.5		ns				
t _h	Hold time, data after CLK↑		0		0		ns		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	չ = 25°C	;	MIN	MAX	UNIT
FARAWIETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	IVIAA	ONIT
4			C _L = 15 pF	100	160		80		MHz
f _{max}		Ī	C _L = 50 pF	80	140		65		IVITIZ
^t PLH	DDE OLD	0 5	C _L = 15 pF		7.6	10.4	1	12	ns
t _{PHL}	PRE or CLR	Q or Q	OL = 13 pr		7.6	10.4	1	12	115
^t PLH	CLK	Q or Q	C _I = 15 pF		5.8	7.8	1	9	no
^t PHL	CLK	Q or Q	CL = 13 pr		5.8	7.8	1	9	ns
^t PLH	PRE or CLR	0 5	C: - 50 pF		8.1	11.4	1	13	20
t _{PHL}	PRE OF CLR	Q or Q	Q or \overline{Q} $C_L = 50 \text{ pF}$		8.1	11.4	1	13	ns
^t PLH	CLK	Q or $\overline{\mathbb{Q}}$	C _L = 50 pF		6.3	8.8	1	10	no
^t PHL	CLK	QUIQ	GL = 50 PF		6.3	8.8	1	10	ns

noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	MIN	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH	4		V
V _{IH(D)}	High-level dynamic input voltage	2		V
V _{IL(D)}	Low-level dynamic input voltage		0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

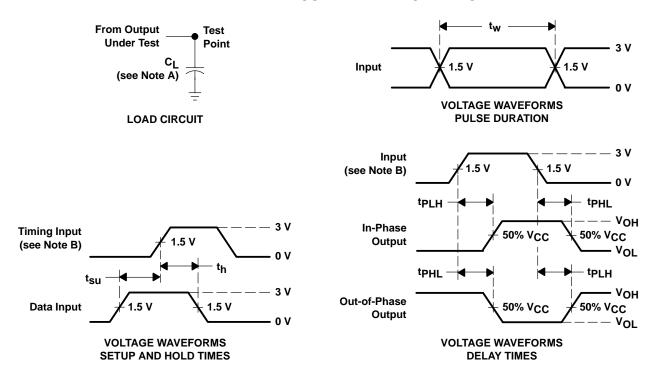
operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

		PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
Ī	C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	32	pF



SCLS495-JUNE 2003

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 3 \text{ ns}$.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74AHCT74MDREP	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT74MEP
SN74AHCT74MDREP.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT74MEP
SN74AHCT74MPWREP	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT74EP
SN74AHCT74MPWREP.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT74EP
V62/03659-01XE	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT74EP
V62/03659-01YE	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT74MEP

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

OTHER QUALIFIED VERSIONS OF SN74AHCT74-EP:

■ Catalog : SN74AHCT74

• Military : SN54AHCT74

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

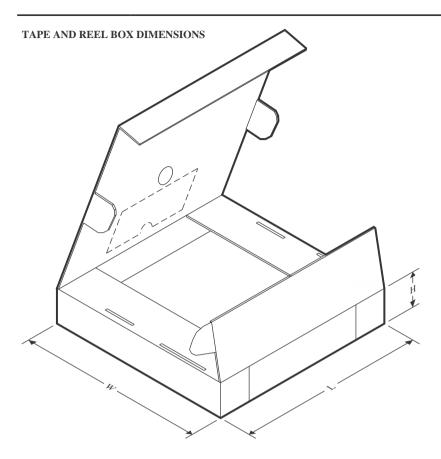


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT74MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT74MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT74MDREP	SOIC	D	14	2500	340.5	336.1	32.0
SN74AHCT74MPWREP	TSSOP	PW	14	2000	353.0	353.0	32.0

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025